

N-Channel Enhancement-Mode Vertical DMOS FET

Features

- · Free from Secondary Breakdown
- · Low Power Drive Requirement
- · Ease of Paralleling
- Low C_{ISS} and Fast Switching Speeds
- · Excellent Thermal Stability
- · Integral Source-Drain Diode
- · High Input Impedance and High Gain

Applications

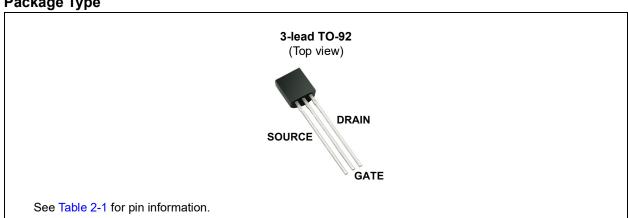
- · Motor Controls
- · Converters
- · Amplifiers
- · Switches
- · Power Supply Circuits
- · Drivers (Relays, Hammers, Solenoids, Lamps, Memories, Displays, Bipolar Transistors, etc.)

General Description

VN2406 Enhancement-mode (normally-off) transistors use a vertical DMOS structure and a well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally induced secondary breakdown.

Microchip's vertical DMOS FETs are ideally suited for a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Type



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Drain-to-Source Voltage	BV _{DSS}
Drain-to-Gate Voltage	BVncs
Gate-to-Source Voltage	200
Operating Ambient Temperature, T _A	
Storage Temperature, T _S	

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^{\circ}$ C unless otherwise specified. All DC parameters are 100% tested at 25°C unless otherwise stated. Pulse test: 300 µs pulse, 2% duty cycle

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
Drain-to-Source Breakdown Voltage	BV _{DSS}	240	_	_	V	$V_{GS} = 0V, I_D = 100 \mu A$
Gate Threshold Voltage	V _{GS(th)}	8.0	_	2	V	$V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$
Gate Body Leakage Current	I _{GSS}	-	_	100	nA	V_{GS} = 20V, V_{DS} = 0V
		_	_	10	μΑ	V _{GS} = 0V, V _{DS} = 120V
Zero-Gate Voltage Drain Current	I _{DSS}	_	_	500	μΑ	V _{GS} = 0V, V _{DS} = 120V, T _A = 125°C (Note 1)
On-State Drain Current	I _{D(ON)}	1	_	_	Α	V _{GS} = 10V, V _{DS} = 15V
Static Drain-to-Source On-State Resistance	D		_	10	Ω	V_{GS} = 2.5V, I_{D} = 100 mA
Static Dialif-to-Source Off-State Resistance	R _{DS(ON)}	l	_	6	Ω	V_{GS} = 10V, I_{D} = 500 mA
Change in R _{DS(ON)} with Temperature	$\Delta R_{DS(ON)}$	_	1	1.4	%/°C	V _{GS} = 10V, I _D = 500 mA (Note 1)

Note 1: Specification is obtained by characterization and is not 100% tested.

AC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^{\circ}C$ unless otherwise specified. All AC parameters are not 100% sample tested.									
Parameter		Min.	Тур.	Max.	Unit	Conditions			
Forward Transconductance	G _{FS}	300	_	_	mmho	V _{DS} = 10V, I _D = 500 mA			
Input Capacitance	C _{ISS}	_	-	125	рF	V _{GS} = 0V,			
Common-Source Output Capacitance	Coss	_	_	50	рF	V _{DS} = 25V,			
Reverse Transfer Capacitance	C _{RSS}	_	_	20	pF	f = 1 MHz			
Turn-On Delay Time	t _{d(ON)}	_	-	8	ns				
Rise Time	t _r	_	_	8	ns	$V_{DD} = 60V,$			
Turn-Off Delay Time	t _{d(OFF)}	_	_	23	ns	$I_D = 400 \text{ mA},$ $R_{GEN} = 25\Omega$			
Fall Time	t _f	_	_	24	ns	- GEN			
DIODE PARAMETER									
Diode Forward Voltage Drop	V_{SD}	_	1.2	_	V	V _{GS} = 0V, I _{SD} = 800 mA (Note 1)			

Note 1: Unless otherwise stated, all DC parameters are 100% tested at 25°C. Pulse test: 300 μs pulse, 2% duty cycle

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T _A	-55	_	+150	°C	
Storage Temperature	T _S	-55	_	+150	°C	
PACKAGE THERMAL RESISTANCE						
3-lead TO-92	θ_{JA}	_	132	_	°C/W	

THERMAL CHARACTERISTICS

Package	I _D (Note 1) (Continuous) (mA)	I _D (Pulsed) (A)	Power Dissipation at T _A = 25°C (W)	I _{DR} (Note 1) (mA)	I _{DRM} (A)
3-lead TO-92	190	1.7	1	190	1.7

Note 1: I_D (continuous) is limited by maximum rated T_J .

VN2406

2.0 PIN DESCRIPTION

The details on the pins of VN2406 are listed in Table 2-1. Refer to **Package Type** for the location of pins.

TABLE 2-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description						
1	Source	Source						
2	Gate	Gate						
3	Drain	Drain						

3.0 FUNCTIONAL DESCRIPTION

Figure 3-1 illustrates the switching waveforms and test circuit for VN2406.

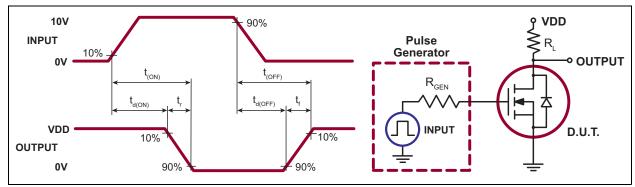


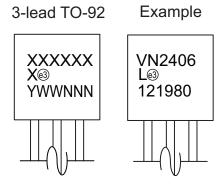
FIGURE 3-1: Switching Waveforms and Test Circuit.

TABLE 3-1: PRODUCT SUMMARY

BV _{DSS} /BV _{DGS} (V)	R _{DS(ON)} (Maximum) (Ω)	I _{DSS} (Minimum) (A)
240	6	1

4.0 PACKAGING INFORMATION

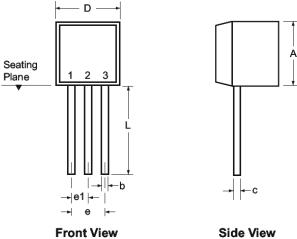
4.1 Package Marking Information



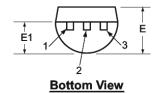
Legend: XX...X Product Code or Customer-specific information
Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')
NNN Alphanumeric traceability code
Pb-free JEDEC® designator for Matte Tin (Sn)
This package is Pb-free. The Pb-free JEDEC designator (e3)
can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

3-Lead TO-92 Package Outline (L/LL/N3)







Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symb	ol	Α	b	С	D	E	E1	е	e1	L
	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
()	MAX	.210	.022 [†]	.022†	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.
* This dimension is not specified in the JEDEC drawing.
† This dimension differs from the JEDEC drawing.

Drawings not to scale.



NOTES:

APPENDIX A: REVISION HISTORY

Revision A (May 2021)

- Converted and merged Supertex Doc# DSFP-VN2406 to Microchip DS20005990A
- · Changed the package marking format
- Removed 3-lead TO-92 L P002, P003, P005, P013, and P014 media types to align packaging specifications with the actual BQM
- Added section(s) to comply with Microchip formatting standards
- Made minor text changes throughout the document

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO Device	<u>XX</u> Packa	age	- X - X Environmental Media Type	Example: a) VN2406L-G:	N-Channel Enhancement-
	Optio	ns		a) VIV2400L-G.	Mode, Vertical DMOS FET, 3-lead TO-92, 1000/Bag
Device:	VN2406	=	N-Channel Enhancement-Mode Vertical DMOS FET		
Package:	L	=	3-lead TO-92		
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package		
Media Type:	(blank)	=	1000/Bag for an L Package		

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